ABSTRACT

WAFER LEVEL THROUGH-HOLE PLUGGING USING MECHANICAL FORMING TECHNIQUE

A wafer is provided having at least one through-hole therein. The at least one through-hole is filled with one or more conductive balls. Thereafter, the wafer is compressed wherein the one or more conductive balls form a conductive plug in the at least one through-hole. After forming the conductive plug in one or more wafers, the wafers can be joined to form a three-dimensional system.

Fig. 1C